

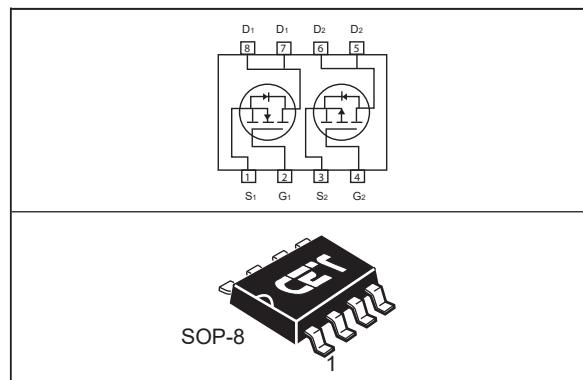
Dual Enhancement Mode Field Effect Transistor (N and P Channel)**FEATURES**

- High power and current handing capability.
- Reliable and rugged.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- Surface mount Package.

APPLICATIONS

- DC Fans.
- Drone.
- Power Bank.

	V_{DSS}	$R_{DS(ON)\text{ typ}}@V_{GS}$	I_D
N Channel	30V	$11.0\text{m}\Omega@V_{GS} = 10\text{V}$	9.7A
		$13.4\text{m}\Omega@V_{GS} = 4.5\text{V}$	8.5A
P Channel	-30V	$17.8\text{m}\Omega@V_{GS} = -10\text{V}$	-7.6A
		$26.2\text{m}\Omega@V_{GS} = -4.5\text{V}$	-6.0A

**ABSOLUTE MAXIMUM RATINGS** $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	N-Channel	P-Channel	Units
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Drain Current-Continuous@ $T_A = 25^\circ\text{C}$ $@T_A = 100^\circ\text{C}$	I_D	9.7 6.1	-7.6 -4.8	A
Drain Current-Pulsed ^a	I_{DM}	38.8	-30.4	A
Maximum Power Dissipation	P_D	2.0		W
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W



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N-Channel Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 9\text{A}$		11.0	13.2	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 5\text{A}$		13.4	17.4	$\text{m}\Omega$
Gate Input Resistance	R_g	f=1MHz,open Drain		2.5		Ω
Dynamic Characteristics^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		735		pF
Output Capacitance	C_{oss}			145		pF
Reverse Transfer Capacitance	C_{rss}			110		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 15\text{V}, I_D = 9\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 3\Omega$		13		ns
Turn-On Rise Time	t_r			7		ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			45		ns
Turn-Off Fall Time	t_f			18		ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 15\text{V}, I_D = 9\text{A}, V_{\text{GS}} = 4.5\text{V}$		9.3		nC
Gate-Source Charge	Q_{gs}			1.8		nC
Gate-Drain Charge	Q_{gd}			4.8		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				1.6	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 1.5\text{A}$			1.2	V
Notes :						
a.Repetitive Rating : Pulse width limited by maximum junction temperature.						
b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.						
c.Guaranteed by design, not subject to production testing.						



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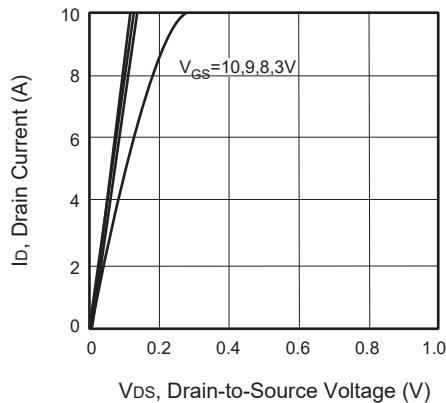
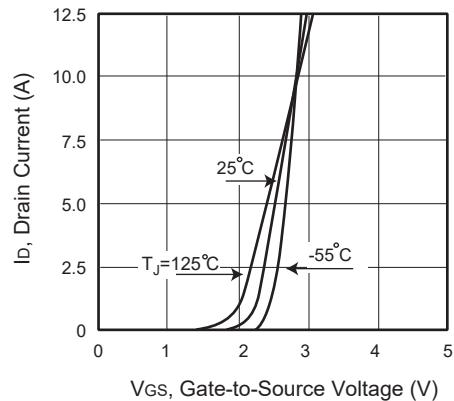
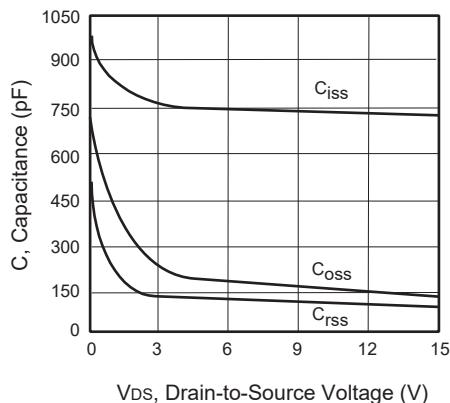
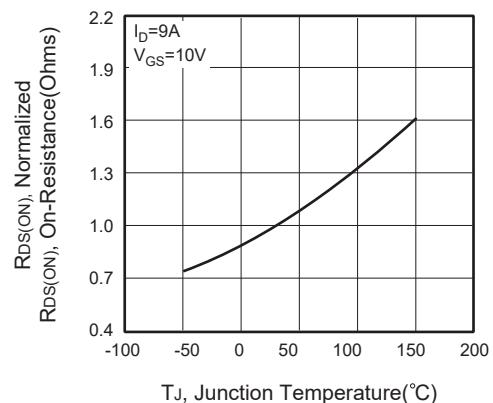
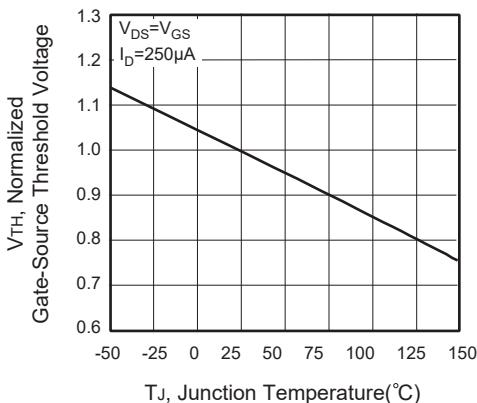
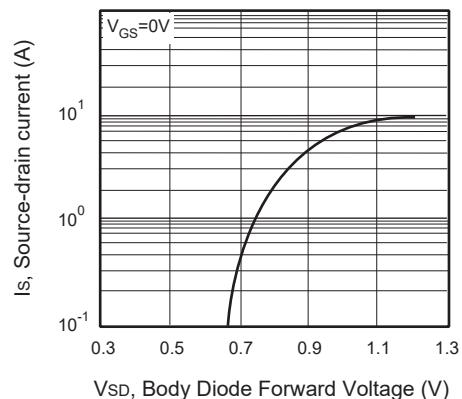
P-Channel Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

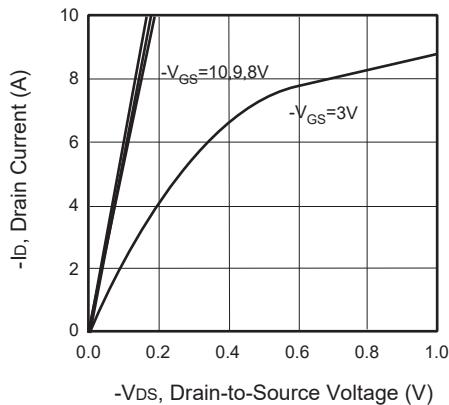
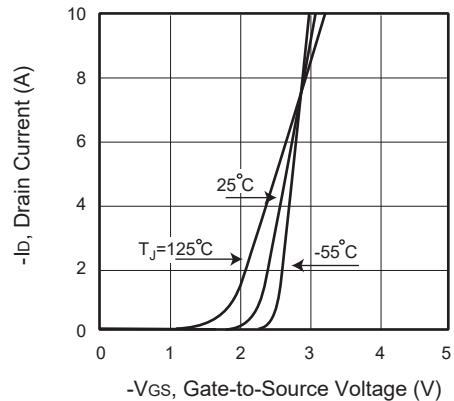
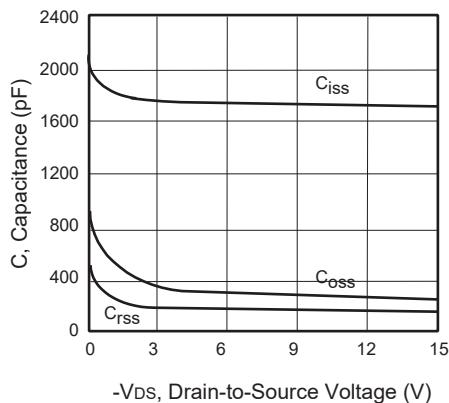
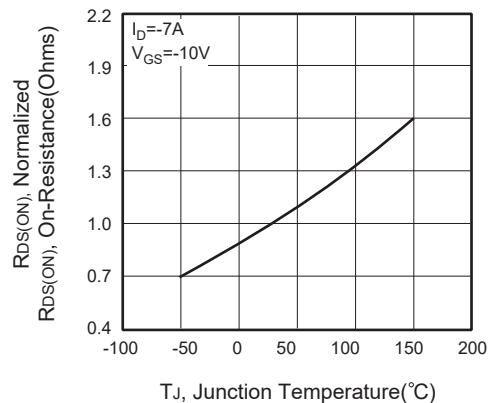
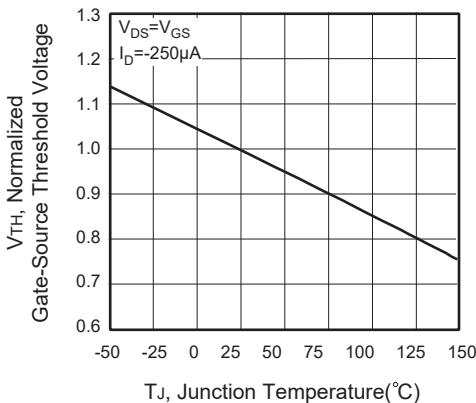
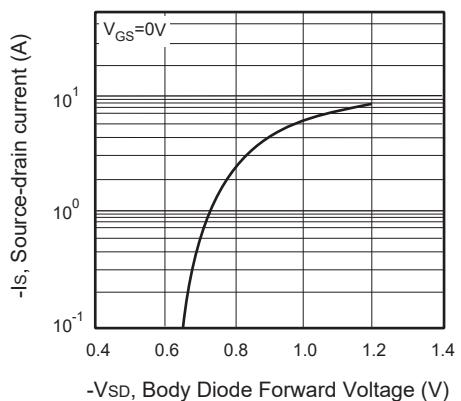
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = -250\mu\text{A}$	-1		-3	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -7\text{A}$		17.8	21.4	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -4\text{A}$		26.2	34.0	$\text{m}\Omega$
Gate Input Resistance	R_g	f=1MHz,open Drain		8.7		Ω
Dynamic Characteristics^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		1710		pF
Output Capacitance	C_{oss}			260		pF
Reverse Transfer Capacitance	C_{rss}			185		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -24\text{V}, I_D = -1\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GEN}} = 6\Omega$		16		ns
Turn-On Rise Time	t_r			8		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			75		ns
Turn-Off Fall Time	t_f			36		ns
Total Gate Charge	Q_g	$V_{\text{DS}} = -24\text{V}, I_D = -1\text{A}, V_{\text{GS}} = -4.5\text{V}$		18		nC
Gate-Source Charge	Q_{gs}			3.4		nC
Gate-Drain Charge	Q_{gd}			7.1		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				-1.6	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = -1.5\text{A}$			-1.2	V

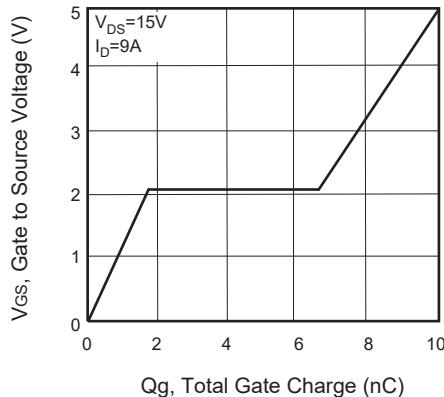
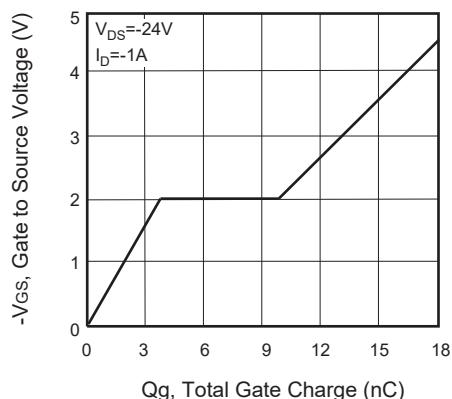
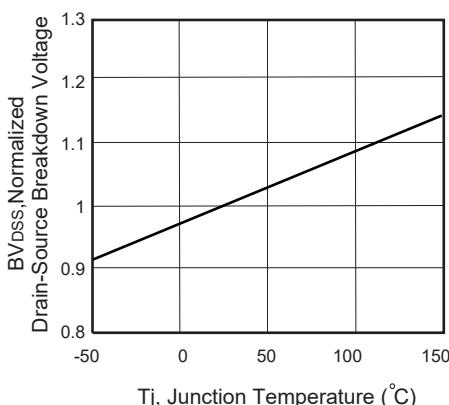
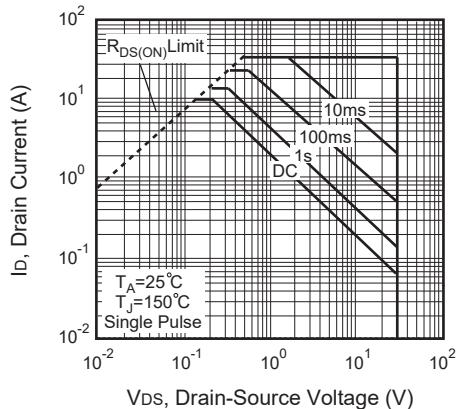
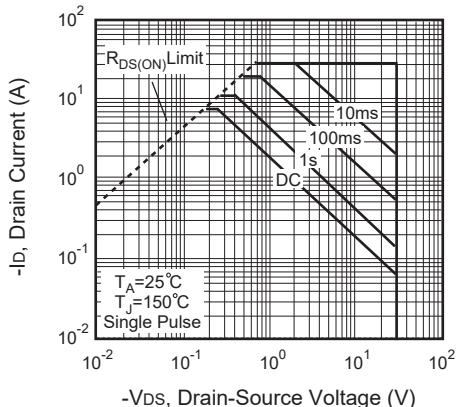
Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

c.Guaranteed by design, not subject to production testing.

N-CHANNEL

Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. Capacitance

Figure 4. On-Resistance Variation with Temperature

Figure 5. Gate Threshold Variation with Temperature

Figure 6. Body Diode Forward Voltage Variation with Source Current

P-CHANNEL

Figure 7. Output Characteristics

Figure 8. Transfer Characteristics

Figure 9. Capacitance

Figure 10. On-Resistance Variation with Temperature

Figure 11. Gate Threshold Variation with Temperature

Figure 12. Body Diode Forward Voltage Variation with Source Current

N-CHANNEL

Figure 13. Gate Charge
P-CHANNEL

Figure 15. Gate Charge

Figure 17. Breakdown Voltage Variation VS Temperature

Figure 14. Maximum Safe Operating Area

Figure 16. Maximum Safe Operating Area

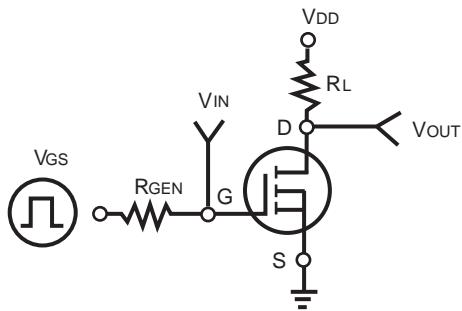


Figure 18. Switching Test Circuit

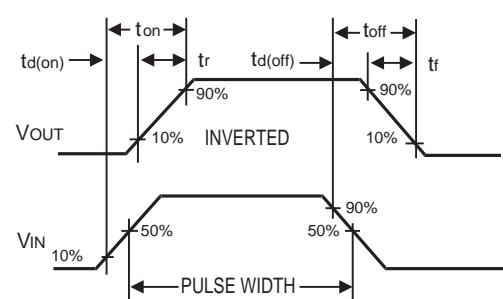


Figure 19. Switching Waveforms

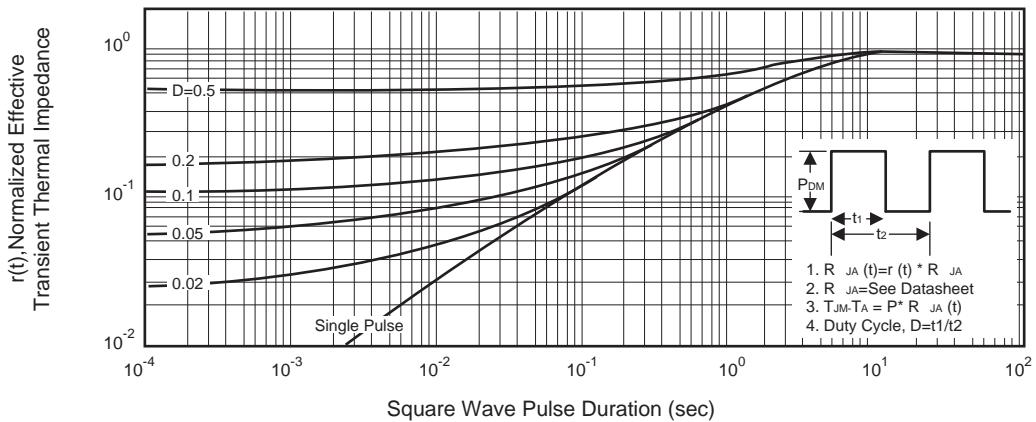
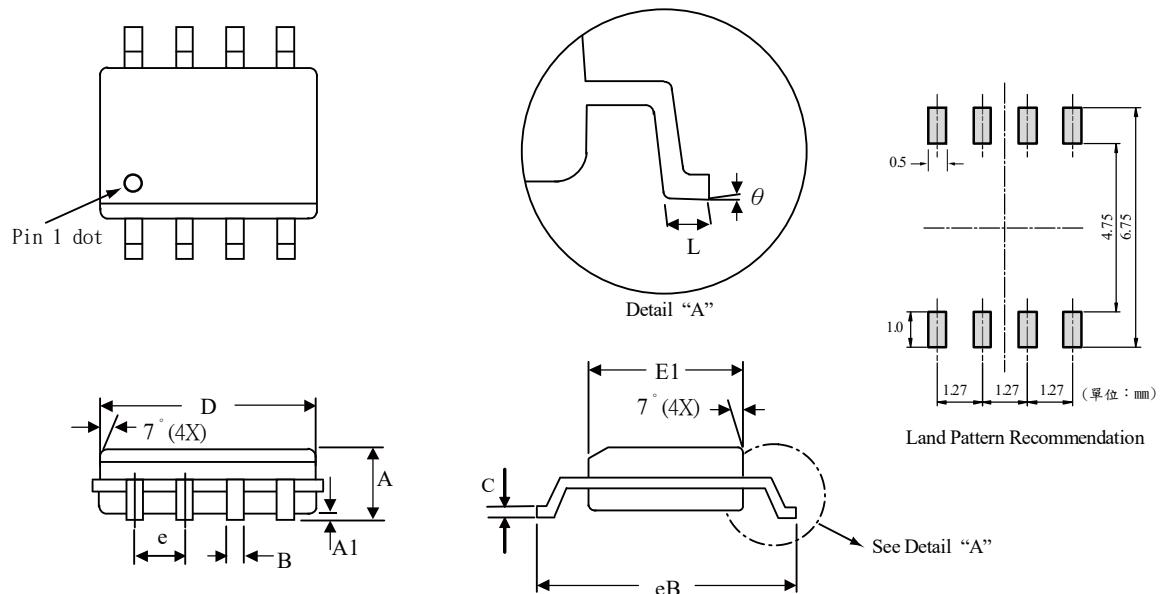


Figure 20. Normalized Thermal Transient Impedance Curve

SO-8 產品外觀尺寸圖 (Product Outline Dimension)


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
B	0.31	0.51	0.012	0.020
C	0.17	0.25	0.007	0.010
D	4.69	5.00	0.185	0.197
E1	3.70	4.06	0.146	0.160
eB	5.80	6.20	0.228	0.244
e	1.27		0.050	
L	0.40	0.95	0.016	0.037
θ	0°	8°	0°	8°